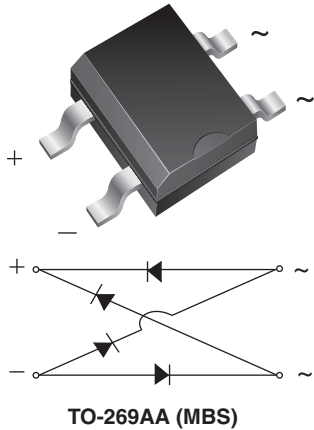


Miniature Glass Passivated Fast Recovery Surface Mount Bridge Rectifier



FEATURES

- UL recognition, file number E54214
- Saves space on printed circuit boards
- Ideal for automated placement
- High surge current capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



RoHS
COMPLIANT

TYPICAL APPLICATIONS

General purpose use in AC/DC bridge full wave rectification for power supply, lighting ballaster, battery charger, home appliances, office equipment, and telecommunication applications.

MECHANICAL DATA

Case: TO-269AA (MBS)

Molding compound meets UL 94 V-0 flammability rating
Base P/N-E3 - RoHS-compliant, commercial grade

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix meets JESD 201 class 1A whisker test

Polarity: As marked on body

PRIMARY CHARACTERISTICS	
Package	TO-269AA (MBS)
$I_{F(AV)}$	0.5 A
V_{RRM}	200 V, 400 V, 600 V
I_{FSM}	35 A
I_R	5 μ A
V_F at $I_F = 0.4$ A	1.0 V
T_J max.	150 °C
Diode variations	Quad

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)					
PARAMETER	SYMBOL	MB2S	MB4S	MB6S	UNIT
Device marking code		2	4	6	
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	V
Maximum RMS voltage	V_{RMS}	140	280	420	V
Maximum DC blocking voltage	V_{DC}	200	400	600	V
Maximum average forward output rectified current (fig. 1)	$I_{F(AV)}$	on glass-epoxy PCB ⁽¹⁾			A
		on aluminum substrate ⁽²⁾			
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	35			A
Rating for fusing ($t < 8.3$ ms)	I^2t	5.0			A ² s
Operating junction and storage temperature range	T_J, T_{STG}	- 55 to + 150			°C

Notes

⁽¹⁾ On glass epoxy PCB mounted on 0.05" x 0.05" (1.3 mm x 1.3 mm) pads

⁽²⁾ On aluminum substrate PCB with an area of 0.8" x 0.8" (20 mm x 20 mm) mounted on 0.05" x 0.05" (1.3 mm x 1.3 mm) solder pad

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS	SYMBOL	MB2S	MB4S	MB6S	UNIT
Maximum instantaneous forward voltage per diode	$I_F = 0.4\text{ A}$	V_F	1.0			V
Maximum DC reverse current at rated DC blocking voltage per diode	$T_A = 25\text{ }^\circ\text{C}$	I_R	5.0			μA
	$T_A = 125\text{ }^\circ\text{C}$		100			
Typical junction capacitance per diode	4.0 V, 1 MHz	C_J	13			pF

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)					
PARAMETER	SYMBOL	MB2S	MB4S	MB6S	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)}$	85			$^\circ\text{C/W}$
	$R_{\theta JA}^{(2)}$	70			
	$R_{\theta JL}^{(1)}$	20			

Notes

- (1) On glass epoxy PCB mounted on 0.05" x 0.05" (1.3 mm x 1.3 mm) pads
- (2) On aluminum substrate PCB with an area of 0.8" x 0.8" (20 mm x 20 mm) mounted on 0.05" x 0.05" (1.3 mm x 1.3 mm) solder pad

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
MB2S-E3/45	0.22	45	100	Tube
MB2S-E3/80	0.22	80	3000	13" diameter paper tape and reel

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

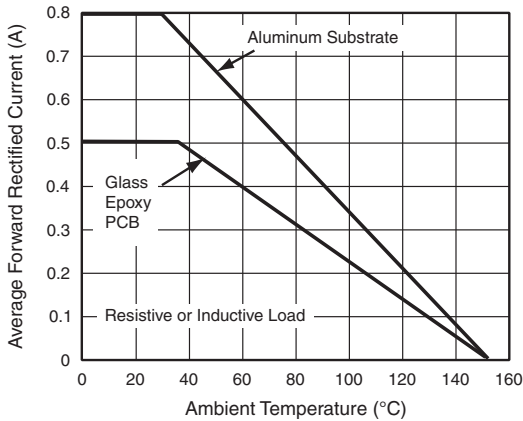


Fig. 1 - Derating Curve for Output Rectified Current

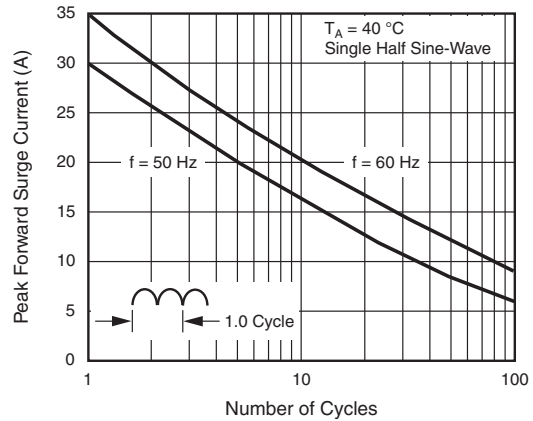


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current Per Diode

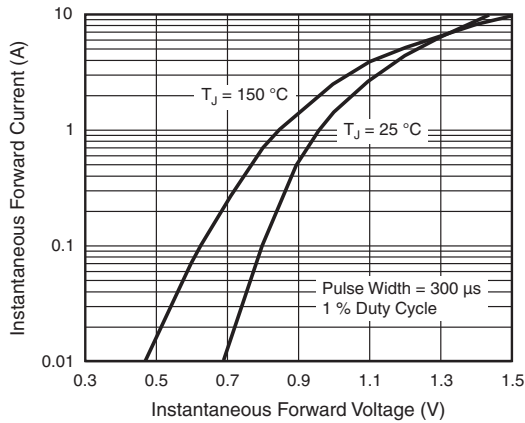


Fig. 3 - Typical Forward Voltage Characteristics Per Diode

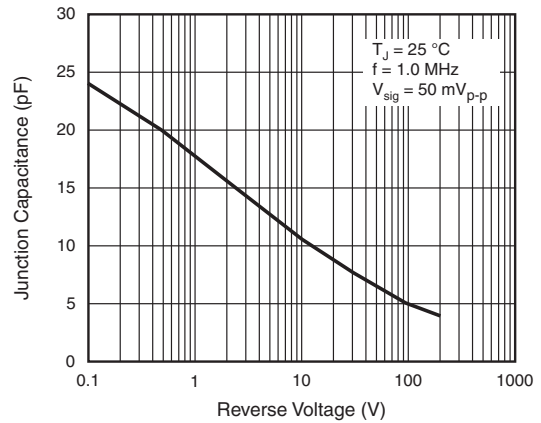


Fig. 5 - Typical Junction Capacitance Per Diode

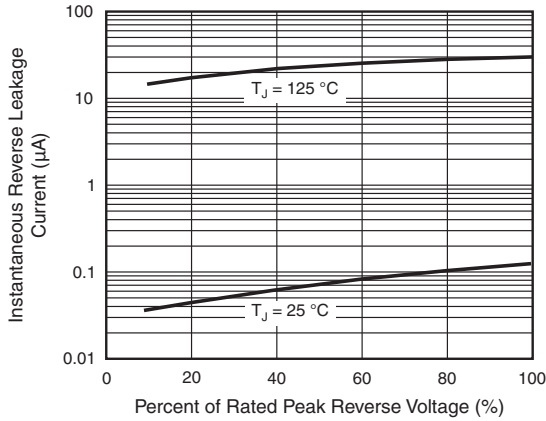
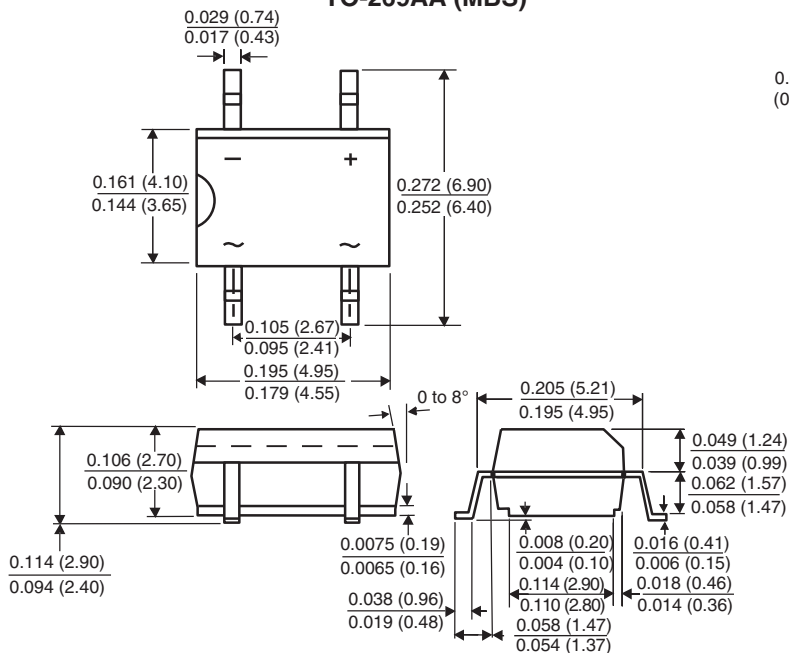


Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

TO-269AA (MBS)



Mounting Pad Layout

